









EFFICIENT PRODUCTION SPEED



MODULAR TOP-DOWN BUILD PLATFORM



OPEN PROCESS PARAMETERS MACHINE



## **SPECIFICATIONS**

Number of DLP Heads	1 or 2 heads
Applications	Investment casting related applications / Technical ceramics / Open for R&D*
Technology	UV-LED DLP, 405 nm wavelength (365 and 385 nm version on demand)
Materials	Qualified with Silica and Alumina slurries from Sintx
Max. Build envelope size (LxWxH)	300 x 445 x 350 mm 10.3 x 12.9 x 13.7 inches
Native pixel size (X,Y)	42 μm (0.0016 inches)
Layer thickness*	50 – 175 μm 0.001 to 0.006 inches
Platform type	Perforated metal platform
Build platform (LxW)	From 75 x 40 mm up to 300 x 445 mm
Vat build height	Up to 350 mm - Starts as low as 500 mL initial fill
Printer size (LxWxH)	855 x 1100 x 1780 mm 33.7 x 43.3 x 70.1 inches
Weight	510 Kg 1125 lbs.
Power requirements	210 – 240 VAC, 8-12A, 50/60 Hz

FOR TAILORED SOLUTIONS TO MEET SPECIFIC MATERIAL REQUIREMENTS OR APPLICATIONS, EXPLORE OUR ALTERNATIVE WAVELENGTH OPTION CERAM PRO 385/385+ AND CERAM PRO 365 (including a specific material offer)

<sup>\*</sup> Please note that the application is contingent upon factors including geometry, build style, and material, and variations in these elements may affect outcomes

